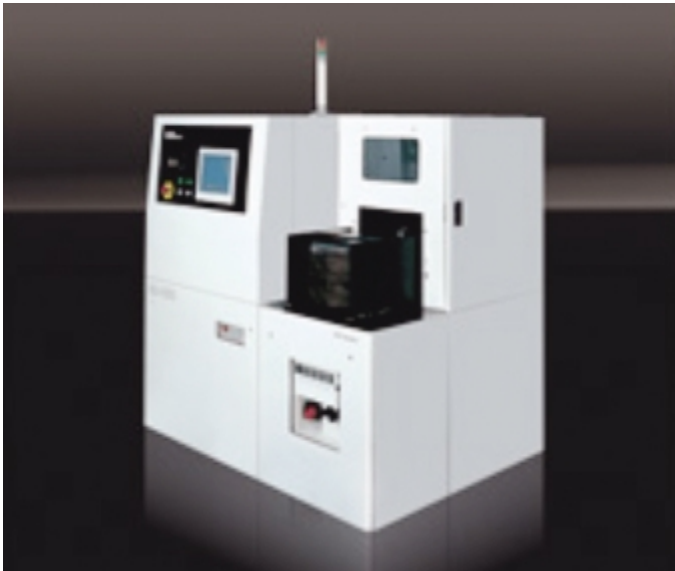


300mm Fully-Automatic UV Irradiation System

# RAD-2010F/12



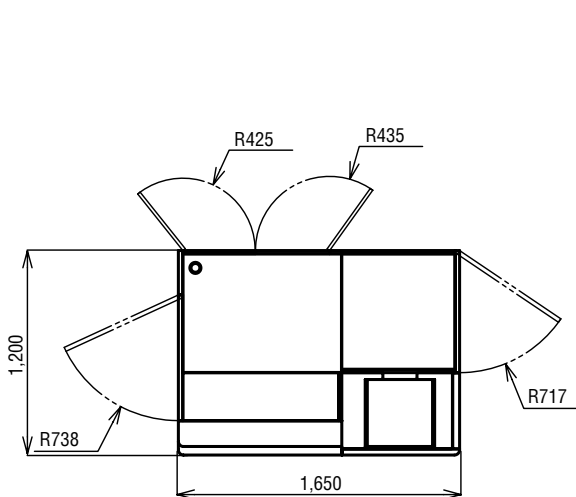
## Outline

- Fully-automatic UV irradiation system used for curing UV type dicing tape.
- Applicable for ring frame sizes used for 200mm and 300mm wafers.

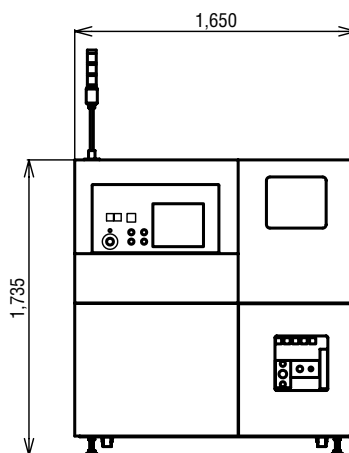
- Options**
- Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM)
  - Barcode Reader for Selecting Recipes
  - Barcode Reader for Reading Ring Frame ID
  - Visual Inspection Support System
  - Double Loader/Unloader

- Suitable Tapes**
- Dicing tape : Adwill D series
  - Dicing die bonding tape : Adwill LE Tape

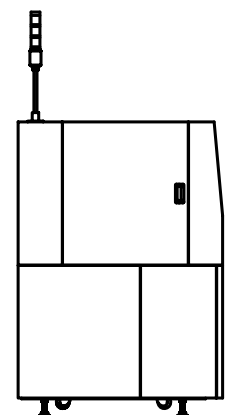
## External View



Top View



Front View



Left Side View

Unit:mm

## Facility

<b>Power Supply</b>	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
<b>Air Supply</b>	Power consumption	: 5.0kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >300L/min (ANR)
<b>Nitrogen Source</b>	Nitrogen pressure	: 0.29MPa
	Nitrogen consumption	: 30-50L/min (ANR)

**Applicable Wafer Size** 200mm, 300mm

**Size**  
Width : 1,650mm  
Depth : 1,200mm  
Height : 1,735mm  
(excluding the signal tower)

**Weight** 1,200kg

**UPH** 90wafers/hour

The above processing capacity is based on following conditions:

Wafer	: 300mm diameter non-polished mirror wafer
Ring frame	: for 300mm wafer



**LINTEC Corporation** *Linking your dreams*

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